

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	34	((428/323).CCLS.) or ((428/673).CCLS.) or ((428/402).CCLS.) or ((428/645).CCLS.) or ((524/432).CCLS.) or ((524/495).CCLS.) or ((524/437).CCLS.)) and ((thermal adj interface) or (phase adj change)) and (fusible or melted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:24
L2	1	((428/323).CCLS.) or ((428/673).CCLS.) or ((428/402).CCLS.) or ((428/645).CCLS.) or ((524/432).CCLS.) or ((524/495).CCLS.) or ((524/437).CCLS.)) and ((thermal adj interface) or (phase adj change)) and (fusible or melted) and columnar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:24
L3	26	(Jayaraman.IN. or Konig.IN. or Dani.IN.) and ((thermal adj interface) or (phase adj change))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:25
L4	2	(Jayaraman.IN. or Konig.IN. or Dani.IN.) and ((thermal adj interface) or (phase adj change)) and columnar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:25
S1	36415	(thermal adj interface) or (phase adj change)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:54
S2	1	((thermal adj interface) or (phase adj change)) and (filler near fusible)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/07/18 18:25
S3	1	(thermal adj interface) and (phase adj change adj polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/27 18:44
S4	93	(phase adj change) near polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:24
S5	2	((phase adj change) near polymer) and (thermal adj interface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/27 18:28

S6	55	(thermal adj interface) and (phase adj change) and filler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/27 18:45
S7	2	(thermal adj interface) and (phase adj change) and (fusible near filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/01 16:13
S8	44	(thermal adj interface adj material) and (phase adj change) and filler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/08/27 18:47
S9	20	(lead or cadmium or mercury or antimony or arsenic) and (fusible near filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/01 16:14
S10	37657	(thermal adj interface) or (phase adj change)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/27 15:20
S11	2	((lead or cadmium or mercury or antimony or arsenic) and (fusible near filler)) and ((thermal adj interface) or (phase adj change))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/01 16:18
S12	6	((lead or cadmium or mercury or antimony or arsenic) and (fusible near filler)) and phase	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/01 16:19
S13	20	(lead or cadmium or mercury, antimony or arsenic) and (fusible near filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/01 16:28
S14	37735	(thermal adj interface) or (phase adj change)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:34
S15	315	Jayaraman.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:35

S16	2306	Konig.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:35
S17	237	Dani.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:35
S18	2852	Jayaraman.IN. or Konig.IN. or Dani.IN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:35
S19	10	(Jayaraman.IN. or Konig.IN. or Dani.IN.) and ((thermal adj interface) or (phase adj change))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:24
S20	3304	(428/323).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:37
S21	583	(428/673).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:37
S22	2201	(428/402).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:37
S23	296	(428/645).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:37
S24	1220	(524/432).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:38
S25	1519	(524/495).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:38

S26	1224	(524/437).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:38
S27	9951	((428/323).CCLS.) or ((428/673).CCLS.) or ((428/402).CCLS.) or ((428/645).CCLS.) or ((524/432).CCLS.) or ((524/495).CCLS.) or ((524/437).CCLS.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 10:39
S28	87	((428/323).CCLS.) or ((428/673).CCLS.) or ((428/402).CCLS.) or ((428/645).CCLS.) or ((524/432).CCLS.) or ((524/495).CCLS.) or ((524/437).CCLS.)) and ((thermal adj interface) or (phase adj change))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/10/02 11:41
S29	23	((428/323).CCLS.) or ((428/673).CCLS.) or ((428/402).CCLS.) or ((428/645).CCLS.) or ((524/432).CCLS.) or ((524/495).CCLS.) or ((524/437).CCLS.)) and ((thermal adj interface) or (phase adj change)) and (fusible or melted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/07 10:21
S30	11302	alloy with(melting adj point)	US-PGPUB; USPAT	OR	ON	2004/03/04 15:24
S31	0	(fusible adj filler) and (alloy with(melting adj point))	US-PGPUB; USPAT	OR	ON	2004/08/30 15:40
S32	627	fusible and (alloy with(melting adj point))	US-PGPUB; USPAT	OR	ON	2004/08/27 15:19
S33	4	fusible and (alloy with(melting adj point)) and filler and composition and (thermal adj interface)	US-PGPUB; USPAT	OR	ON	2004/03/04 15:26
S34	56	(thermal adj interface) and (phase adj change) and solder and (fiber or nitride or oxide or graphite)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/27 15:22
S35	0	(fusible adj filler) and (alloy with (melting adj point))	US-PGPUB; USPAT	OR	ON	2004/08/30 15:40
S36	0	(fusible adj filler) and (alloy with (melting adj point))	US-PGPUB; USPAT	OR	ON	2004/08/30 15:40
S37	11	(fusible adj (metal or alloy)) and (alloy same (melting adj point))	US-PGPUB; USPAT	OR	ON	2004/08/30 16:13

S38	11	US-5062896-\$.DID. OR US-4869954-\$.DID. OR US-4914551-\$.DID. OR US-4612601-\$.DID. OR US-4606962-\$.DID. OR US-6365973-\$.DID. OR US-0634013-\$.DID. OR US-6059952-\$.DID. OR US-6114413-\$.DID. OR US-6365973-\$.DID. OR US-6207300-\$.DID. OR US-5213715-\$.DID.	US-PGPUB; USPAT	OR	ON	2005/01/24 15:23
S39	11	US-5062896-\$.DID. OR US-4869954-\$.DID. OR US-4914551-\$.DID. OR US-4612601-\$.DID. OR US-4606962-\$.DID. OR US-6365973-\$.DID. OR US-0634013-\$.DID. OR US-6059952-\$.DID. OR US-6114413-\$.DID. OR US-6365973-\$.DID. OR US-6207300-\$.DID. OR US-5213715-\$.DID.	US-PGPUB; USPAT	OR	ON	2005/01/24 15:23
S40	0	S39 and columnar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:23
S41	2	((phase adj change) near polymer) and columnar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:25
S42	0	WO0211504	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:28
S43	0	WO02-0011504	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:29
S44	0	WO-2002011504-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:30

S45	7923	(thermal adj interface) or (phase adj change) and (columnar or column)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:55
S46	2082	(thermal adj interface) or (phase adj change) and ((columnar or column) adj structure) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:56
S47	2078	(thermal adj interface) or (phase adj change) and ((columnar or column) adj structure) and conductive and (solder or alloy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:57
S48	2074	(thermal adj interface) or (phase adj change) and ((columnar or column) adj structure) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 15:58
S49	1	((((thermal adj interface) or (phase adj change)) near polymer) and ((columnar or column) adj structure) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:09
S50	14	((((thermal adj interface) or (phase adj change)) with polymer) and (columnar or column) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:03
S51	1	((((thermal adj interface) or (phase adj change)) near polymer) and (columnar adj structure) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:10
S52	1	((((thermal adj interface) or (phase adj change)) near polymer) and (columnar with structure) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:11
S53	1	((((thermal adj interface) or (phase adj change)) near polymer) and columnar and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:11
S54	682	columnar and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:12

S55	92	(columnar adj structure) and conductive and (solder or alloy) and interconnect\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:16
S56	9	(columnar adj structure) and conductive and (solder or alloy) and interconnect\$3 and (phase adj change)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/24 16:13